



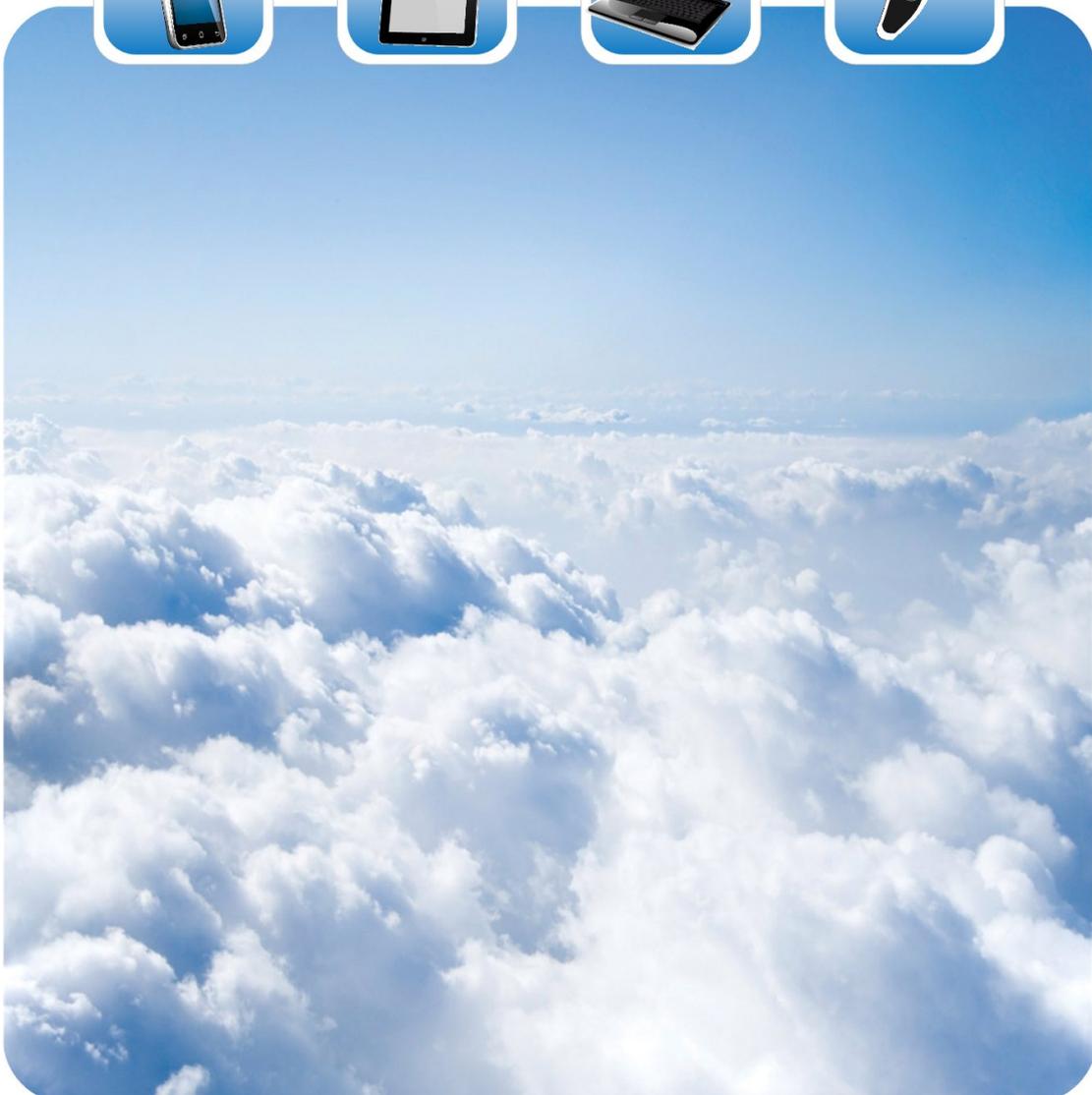
苏州敏芯微电子技术股份有限公司  
MEMSensing Microsystems (Suzhou, China) Co., Ltd.

# Data Sheet

V1.0 / Oct. 2019

## MSM261S3526Z0CM

I<sup>2</sup>S digital output MEMS microphone with Multi-modes



# MSM261S3526Z0CM

I<sup>2</sup>S digital output MEMS microphone



## GENERAL DESCRIPTION

MSM261S3526Z0CM is an omni-directional, Bottom-ported, I<sup>2</sup>S digital output MEMS microphone. It has high performance and reliability.

MSM261S3526Z0CM is available in a 3.50 mm × 2.65 mm × 0.98 mm metal can LGA package. It is SMT compatible with no sensitivity degradation.

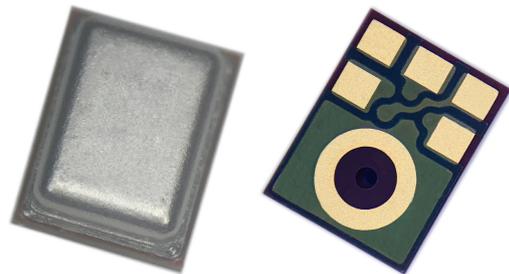
## APPLICATIONS

- ✧ Mobile Phone
- ✧ Laptop
- ✧ Tablet computer
- ✧ Bluetooth headset
- ✧ Earphone
- ✧ Wearable intelligent equipment

## FEATURES

- ✧ Cost effective
- ✧ Digital I<sup>2</sup>S output
- ✧ Low Power Mode
- ✧ Compatible with Sn/Pb and Pb-free solder processes
- ✧ RoHS/Halogen free compliant
- ✧ Sensitivity Matching within +/-1dB

## PRODUCT VIEW





## ABSOLUTE MAXIMUM RATINGS

Parameter	Maximum value	Unit
Supply Voltage	-0.3 to 4.0	V
Sound Pressure Level	140	dB SPL
Storage temperature	-40 to 100	°C

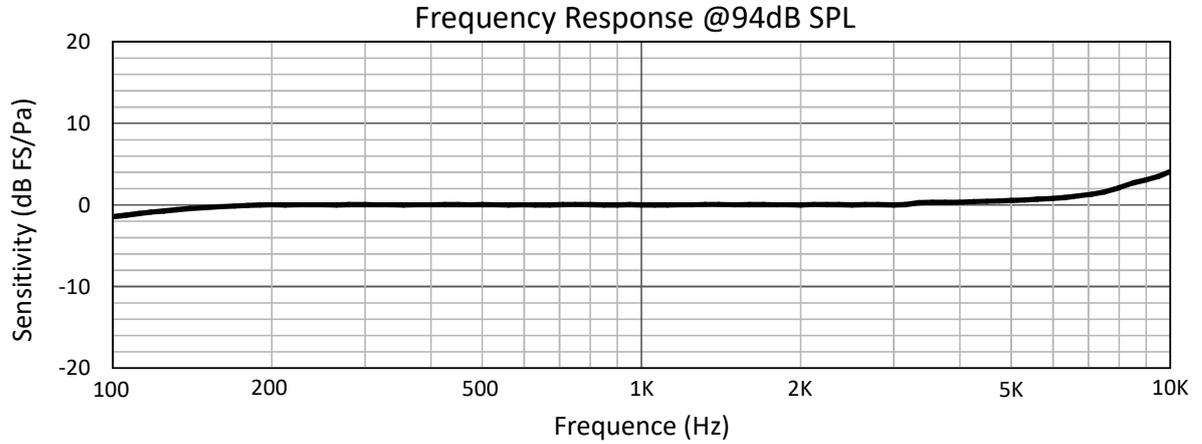
## SPECIFICATIONS

All data taken at 25°C, Relative Humidity 45±5% L/R pin grounded unless otherwise specified  
V<sub>dd</sub>=1.8V, clock frequency=3.072MHz

	Limits			unit	condition
	Min.	Nom.	Max.		
Directivity	Omni directional				
Sensitivity	-27	-26	-25	dB	dBFS @1kHz 1Pa
Operation voltage	1.6		3.6	V	
Freq. range	Refer to the frequency response			Hz	
Sensitivity loss across supply voltage	No change across the voltage range			dB	
Signal to noise ratio	-	64	-	dB	20 kHz bandwidth, A-weighted
THD	-	0.1	-	%	94dB SPL @1kHz S =Nom, Rload > 2 k
AOP	-	120	-	dB SPL	10% THD @1kHz S =Nom, Rload > 2 k
Polarity	increasing sound				Increasing density of 1's
PSR		-72		dBFS(A)	
Current consumption	-	750	1000	μA	Normal mode
	-	400	-	μA	Low power mode
Clock frequency	1.0	3	4.0	MHz	Normal mode
	150		600	KHz	Low power mode
Storage temperature	-40	-	100	°C	
Power-up time	-	6	20	ms	



## TYPICAL FREQUENCY RESPONSE



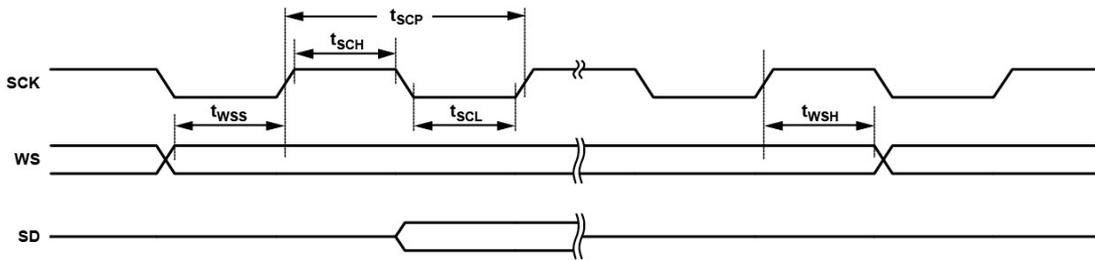
## LOGIC TABLE

	Parameter	Symbol	Min	Max	Unit
Digital	Low Voltage Input(L/R, WS, SCK)	VIL	0	$0.25 \times VDD$	V
Input	High Voltage Input(L/R, WS, SCK)	VIH	$0.7 \times VDD$	VDD	V
SD/Digital Output	Voltage Output Low	VOL	$0.1 \times VDD$	$0.3 \times VDD$	V
	Voltage Output High	VOH	$0.7 \times VDD$	$0.9 \times VDD$	V



## TIMING DIAGRAM

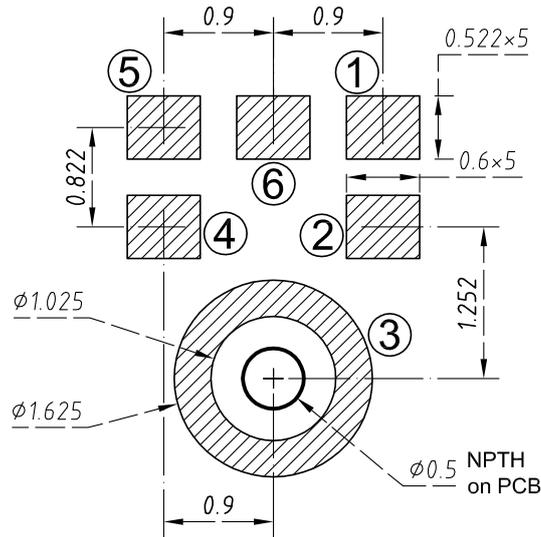
Parameter	Description	Min.	Norm.	Max.	Unit
tSCH	SCK High	—	50	—	ns
tSCL	SCK Low	—	50	—	ns
tSCP	SCK Period	—	325	—	ns
fSCK	SCK Frequency	—	3.072	—	MHz
tWSS	WS Setup	—	0	—	ns
tWSH	WS Hold	—	20	—	ns
fWS	WS Frequency	—	48	—	kHz



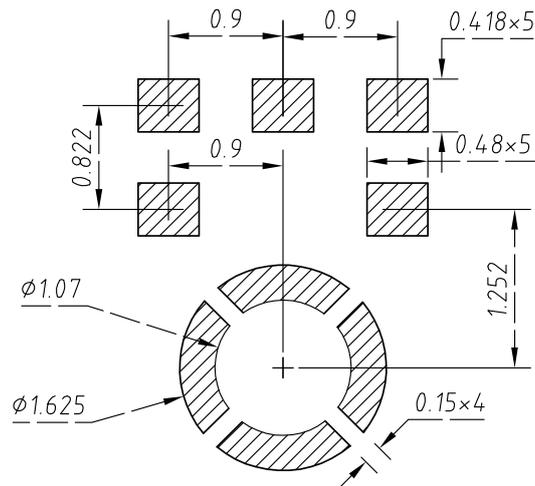


**SMT Parameters:**

**1. Recommend PCB land pattern layout: (unit: mm)**

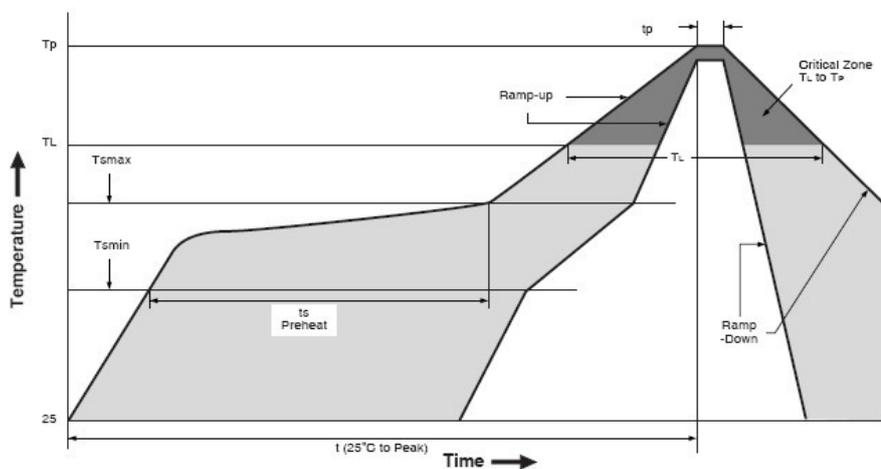


**2. Recommend stencil pattern: (unit: mm)**





### 3. Recommend reflow profile:

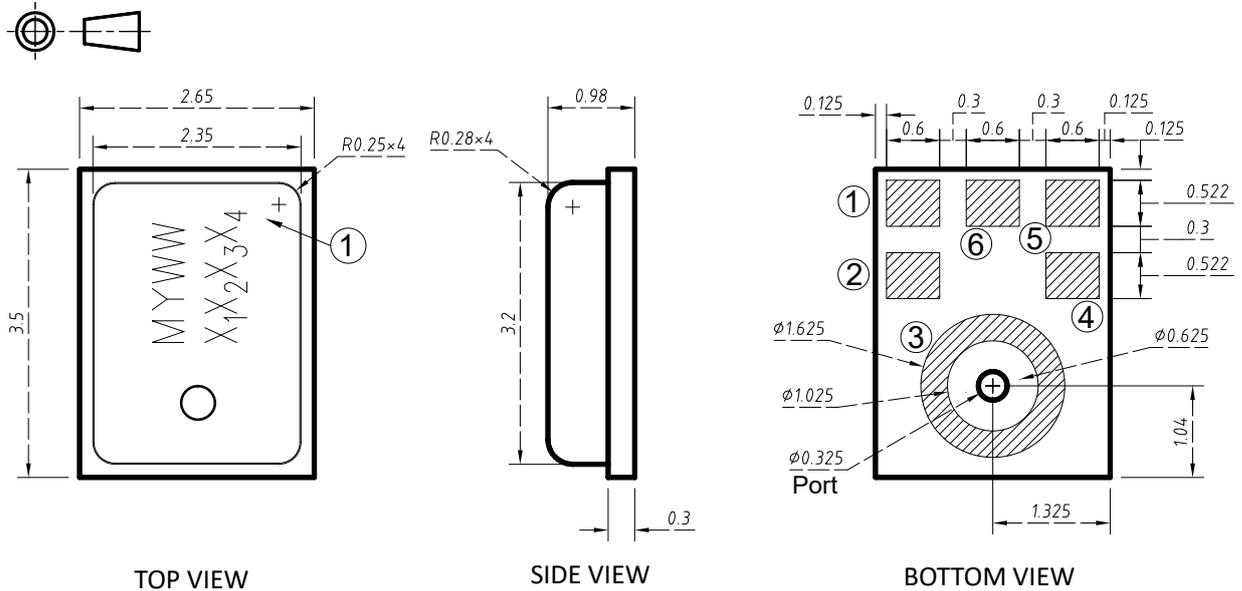


Description	Parameter	Pb free
Average ramp rate	$T_L$ to $T_P$	3 °C/sec max
Preheat		
Minimum temperature	$T_{SMIN}$	150 °C
Maximum temperature	$T_{SMAX}$	200 °C
Time( $T_{SMIN}$ to $T_{SMAX}$ )	$t_s$	60 sec to 180 sec
Ramp-up rate	$T_{SMAX}$ to $T_L$	15 ~ 2 °C/sec
Time maintained above liquidus temperature	$t_L$	60 sec to 150 sec
Liquidus temperature	$T_L$	217 °C
Peak temperature	$T_P$	260 °C
Time within 5°C of actual peak temperature	$t_p$	20 sec to 40 sec
Ramp-down rate	$T_P$ to $T_{smax}$	6 °C/sec max
Time 25 °C ( $t_{25 °C}$ ) to peak temperature	$t$	8 minutes max

NOTE: When MEMS MIC is soldered on PCB, the reflow profile is set according to solder paste and the thickness of PCB etc.



**OUTLINE DIMENSIONS AND PIN DEFINITION:**



Pin	Signal	Type	Description
1	VDD	Power	1.8 to 3.3 V. This pin should be decoupled to Pin 6 with a 0.1 $\mu$ F capacitor.
2	SCK	Input	Serial Data Clock for I <sup>2</sup> S Interface.
3	GND	Ground	Connect to ground on the PCB.
4	L/R	Input	Left/Right Channel Select. When set low, the microphone outputs its signal in the left channel of the I <sup>2</sup> S frame; when set high, the microphone outputs its signal in the right channel.
5	WS	Input	Serial Data-Word Select for I <sup>2</sup> S Interface.
6	SD	Output	Serial Data Output for I <sup>2</sup> S Interface. This pin tristates when not actively driving the appropriate output channel. The SD trace should have a 100 k $\Omega$ pull-down resistor to discharge the line during the time that all microphones on the bus have tristated their outputs.

Item	Dimension	Tolerance
Length (L)	3.50	$\pm 0.10$
Width (W)	2.65	$\pm 0.10$
Height (H)	0.98	$\pm 0.10$
Acoustic Port (AP)	$\varnothing 0.325$	$\pm 0.05$

Dimensions are in millimeters, tolerance is  $\pm 0.15$ mm unless otherwise specified.

MYWW X <sub>1</sub> X <sub>2</sub> X <sub>3</sub> X <sub>4</sub>	M	MEMSensing
	Y	Year(A~Z)
	WW	Week
	X <sub>1</sub> X <sub>2</sub> X <sub>3</sub> X <sub>4</sub>	Serial Number



## ADDITIONAL NOTES

- (A) MSL (moisture sensitivity level) Class 1.
- (B) Maximum of 3 reflow cycles is recommended.
- (C) In order to minimize device damage:
  - Do not board wash or clean after the reflow process.
  - Do not brush board with or without solvents after the reflow process.
  - Do not directly expose to ultrasonic processing, welding, or cleaning.
  - Do not insert any object in port hole of device at any time.
  - Do not apply air pressure into the port hole.
  - Do not pull a vacuum over port hole of the microphone.
  - Do not apply a vacuum when repacking into sealed bags at a rate faster than 0.5 atm/sec.

## STORAGE AND TRANSPORTATION

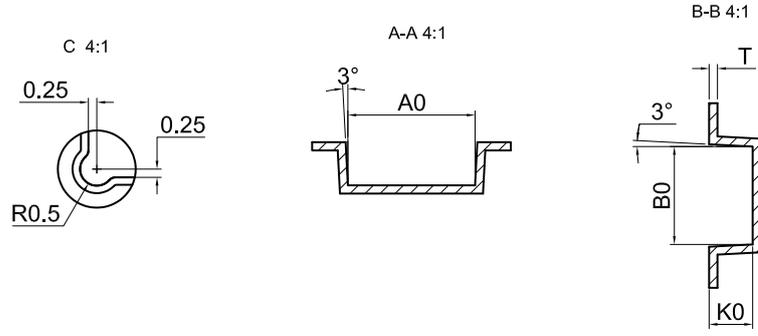
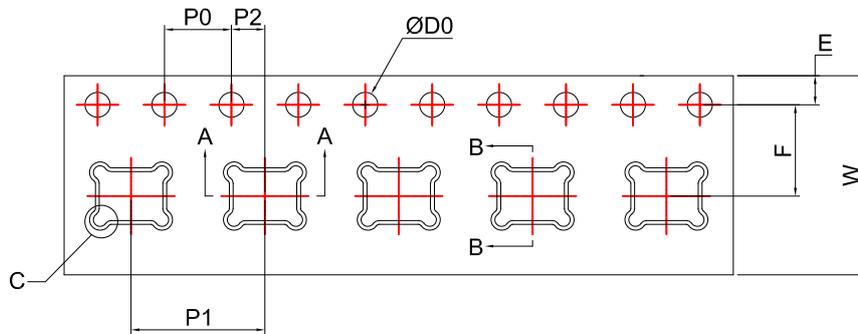
- (A) Keep MEMS MIC in warehouse with less than 75% humidity and without sudden temperature change, acid air, any other harmful air or strong magnetic field.
  - Recommend floor life (out of bag) at factory no more than 4 weeks.
- (B) The MEMS MIC with normal pack can be transported by ordinary conveyances. Please protect products against moist, shock, sunburn and pressure during transportation.

## MATERIALS STATEMENT

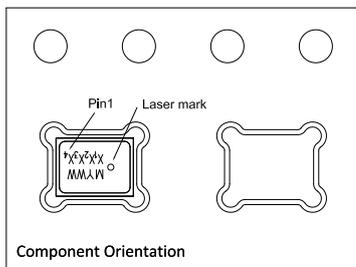
Meets the requirements of the European RoHS and Halogen-Free.



**PACKAGING & MARKING DETAIL:**



Direction of Feed →



ITEM	W	E	F	ØD0	K0
DIM(mm)	12.00±0.30	1.75±0.10	5.50±0.10	1.50 <sup>+0.10</sup> <sub>0</sub>	1.25±0.10
ITEM	P0	10P0	P1	A0	B0
DIM(mm)	4.00±0.10	40.00±0.20	8.00±0.10	3.80±0.10	2.95±0.10
ITEM	P2	T			
DIM(mm)	2.00±0.10	0.25±0.05			

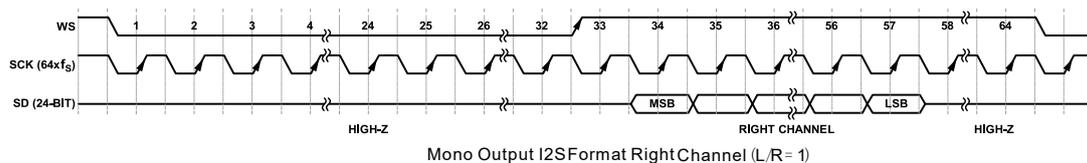
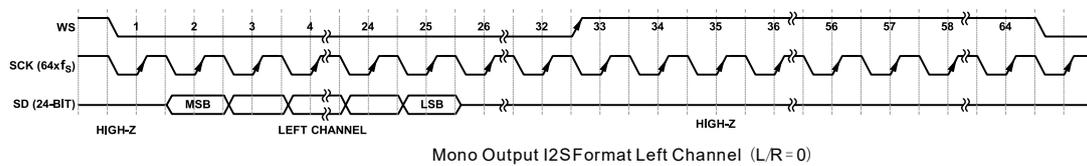
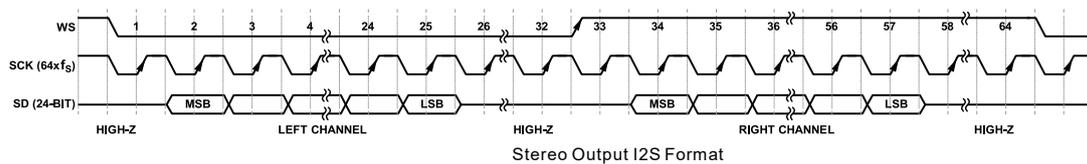
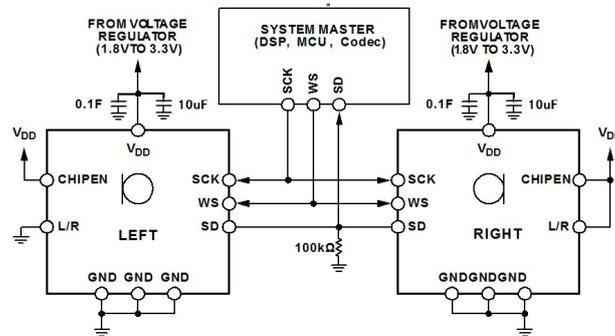
**Note:**

- 1) Dimensions are in mm;
- 2) Don't put the vacuum suction nozzle alignment the port hole;
- 3) Tape & Reel Per EIA-481 standard;
- 4) Label applied to external package and direct to reel;
- 5) Static voltage <100V;

Model Number	Reel Diameter	Quantity Per Reel
MSM261S3526Z0CM	13 inch	5700



## RECOMMENDED INTERFACE CIRCUIT:



## I<sup>2</sup>S DATA INTERFACE

The serial data is in slave mode I<sup>2</sup>S format, which has 24-bit depth in a 32 bit word. In a stereo frame there are 64 SCK cycles, or 32 SCK cycles per data-word. When L/R=0, the output data in the left channel, while L/R=V<sub>DD</sub>, data in the right channel. The output data pin (SD) is tri-stated after the LSB is output so that another microphone can drive the common data line.

### Data Word Length

The output data-word length is 24 bits per channel. The Mic must always have 64 clock cycles for every stereo data-word ( $f_{SCK} = 64 \times f_{WS}$ ).

### Data-Word Format

The default data format is I<sup>2</sup>S, MSB-first. In this format, the MSB of each word is delayed by one SCK cycle from the start of each half-frame.



## RELIABILITY SPECIFICATIONS

Test	Description
Thermal Shock	100 cycles air-to-air thermal shock from -40°C to +125°C with 15 minute soaks.
High Temperature Storage	1,000 hours at +105°C environment
Low Temperature Storage	1,000 hours at -40°C environment
Reflow	5 reflow cycles with peak temperature of +260°C
ESD-HBM	3 discharges of ±2 kV direct contact to I/O pins.
ESD- LID-GND	3 discharges of ±8 kV direct contact to lid while unit is grounded.
ESD-MM	3 discharges of ±200V direct contact to I/O pins.
Vibration	4 cycles of 20 to 2,000 Hz sinusoidal sweep with 20 G peak acceleration lasting 12 minutes in X, Y and Z directions.
Mechanical Shock	3 pulses of 10,000 G in the X, Y and Z direction
High Temperature Bias	1,000 hours at +105°C under bias
Low Temperature Bias	1,000 hours at -40°C under bias
Temperature/Humidity Bias	1,000 hours at +85°C/85% R.H. under bias.
Drop Test	To be no interference in operation after dropped to 1.0cm steel plate 18 times from 1.5 meter height

**NOTE:** Sensitivity should vary within ±3dB from initial sensitivity. (The measurement to be done after 2 hours of conditioning at 20±2 °C, R.H 60%~70%)

**MSM261S3526Z0CM**  
I<sup>2</sup>S digital output MEMS microphone

 苏州敏芯微电子技术股份有限公司  
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**REVISION HISTORY:**

Revision	Subjects (major changes since last revision)	Date
1.0	Initial Release	2019-10-29

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